4-Differential Channel 1:2 Mux/Demux Switch for PCI Express Gen3

The NCN3411 is a 4–Channel differential SPDT switch designed to route PCI Express Gen3 signals. When used in a PCI Express application, the switch can handle up to two PCIe lanes. Due to the ultra–low ON–state capacitance (2 pF typ) and resistance (7.5 Ω typ), these switches are ideal for switching high frequency data signals up to a signal bit rate of 8 Gbps. This switch pinout is designed to be used in BTX form factor desktop PCs and is available in a space–saving 3.5 x 9 x 0.75 mm WQFN42 package.

Features

- V_{DD} Power Supply from 1.5 V to 2.0 V
- 4 Differential Channels 2:1 MUX/DEMUX
- Compatible with PCIe 3.0
- Data Rate: Supports 8 Gbps
- Low Crosstalk -30 dB @ 4 GHz
- Low Bit-to-Bit Skew: 5 ps
- Low R_{ON} Resistance: 13 Ω max
- Low C_{ON} Capacitance: 2 pF
- Low Supply Current: 200 µA
- Off Isolation: -20 dB @ 4 GHz
- Space Saving Small WQFN-42 Package
- This is a Pb–Free Device

Typical Applications

- Notebook Computer
- Desktop computer
- Server/Storage Area Network



Figure 1. Application Schematic



ON Semiconductor®

http://onsemi.com



XXXXX	= Specific Device Code
А	= Assembly Location
WL	= Wafer Lot
YY	= Year
WW	= Work Week
G	= Pb-Free Package

.....

ORDERING INFORMATION

Device	Package	Shipping [†]			
NCN3411MTTWG	WQFN42 (Pb-Free)	2000 / Tape & Reel			

+ For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.





TRUTH TABLE

Function	SEL
A _N to B _N	L
A _N to C _N	Н



PIN FUNCTION AND DESCRIPTION

Pin	Pin Name	Description
2 3	A0+ A0-	Signal I/0, Channel 0, Port A
6 7	A1+ A1–	Signal I/0, Channel 1, Port A
11 12	A2+ A2-	Signal I/0, Channel 2, Port A
15 16	A3+ A3-	Signal I/0, Channel 3, Port A
38 37	B0+ B0-	Signal I/0, Channel 0, Port B
36 35	B1+ B1–	Signal I/0, Channel 1, Port B
29 28	B2+ B2-	Signal I/0, Channel 2, Port B
27 26	B3+ B3-	Signal I/0, Channel 3, Port B
34 33	C0+ C0-	Signal I/0, Channel 0, Port C
32 31	C1+ C1-	Signal I/0, Channel 1, Port C
25 24	C2+ C2-	Signal I/0, Channel 2, Port C
23 22	C3+ C3-	Signal I/0, Channel 3, Port C
9	SEL	Operational Mode Select (When SEL = 0: A \rightarrow B, When SEL = 1: A \rightarrow C)
5, 8, 13, 18, 20, 30, 40, 42	VDD	DC Supply: 1.5 V to 2.0 V
1, 4, 10, 14, 17, 19, 21, 39, 41	GND	Power Ground
Exposed Pad	_	The exposed pad on the backside of package is internally connected to GND. Externally the pad should also be user-connected to GND.

MAXIMUM RATINGS

Parameter	Symbol	Rating	Units
Power Supply Voltage	V _{DD}	-0.5 to 2.5	V _{DC}
Input/Output Voltage Range of the Switch (A_N , B_N , C_N)	V _{IS}	-0.5 to V _{DD}	V _{DC}
Selection Pin Voltages	V _{SEL}	-0.5 to V _{DD}	V _{DC}
Continuous Current Through One Switch	I _{cc}	±120	mA
Maximum Junction Temperature (Note 1)	TJ	150	°C
Operating Ambient Temperature	T _A	-40 to +85	°C
Storage Temperature Range	T _{stg}	-65 to +150	°C
Thermal Resistance, Junction-to-Air	$R_{ heta JA}$	75	°C/W
Latch-up Current (Note 2)	ILU	±100	mA
Human Body Model (HBM) ESD Rating (Note 3)	ESD HBM	7000	V
Machine Model (MM) ESD Rating (Note 3)	ESD MM	400	V
Moisture Sensitivity (Note 4)	MSL	Level 1	_

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect

Recommended Operating Conditions is not implied. Extended exposure to success above the recommended device reliability.
Power dissipation must be considered to ensure maximum junction temperature (T_J) is not exceeded.
Latch up Current Maximum Rating: ±100 mA per JEDEC standard: JESD78.
This device series contains ESD protection and passes the following tests: Human Body Model (HBM) ±7.0 kV per JEDEC standard: JESD22–A114 for all pins. Machine Model (MM) ±400 V per JEDEC standard: JESD22–A115 for all pins.
Moisture Sensitivity Level (MSL): 1 per IPC/JEDEC standard: J–STD–020A.

DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE ($T_A = -40^{\circ}C$ to $+85^{\circ}C$, $V_{DD} = 1.5$ V to 2.0 V, GND = 0V)

Symbol	Pins	Parameters	Conditions (Note 5)	Min.	Typ (Note 6)	Max.	Units
POWER S	UPPLY				•		
V _{DD}	V _{DD} , GND	Supply Voltage Range	With respect to GND	1.5	1.8	2.0	V
I _{DD}	V _{DD} , GND	Quiescent Supply Current	V_{DD} = 2 V, V_{SEL} = GND or V_{DD}		200	300	μA
DATA SW	TCH PERFORM	ANCE					
V _{IS}	A _N , B _N , C _N	Data Input/Output Voltage Range		0		1.2	V
R _{ON}	B _N	On Resistance (B _N)	V_{DD} = 1.5 V, V_{IS} = 0 V to 1.2 V, I_{IS} = 15 mA		7.5	13	Ω
R _{ON}	C _N	On Resistance (C _N)	V_{DD} = 1.5 V, V_{IS} = 0 V to 1.2 V, I _{IS} = 15 mA		8.0	13	Ω
R _{ON(flat)}	B _N	On Resistance Flatness	V_{DD} = 1.5 V, V_{IS} = 0 V to 1.2 V, I_{IS} = 15 mA (Note 7)		0.1	1.24	Ω
R _{ON(flat)}	C _N	On Resistance Flatness	$V_{DD} = 1.5 \text{ V}, V_{IS} = 0 \text{ V to } 1.2 \text{ V},$ $I_{IS} = 15 \text{ mA} \text{ (Note 7)}$		0.1	1.24	Ω
ΔR_{ON}	B _N	On Resistance Matching(B _N)	V_{DD} = 1.5 V, V_{IS} = 0 V, I_{IS} = 15 mA (Note 7)			0.35	Ω
ΔR_{ON}	C _N	On Resistance Matching(C _N)	$V_{DD} = 1.5 \text{ V}, V_{IS} = 0 \text{ V},$ $I_{IS} = 15 \text{ mA} \text{ (Note 7)}$			0.35	Ω
C _{ON}	A _N to B _N , A _N to C _N	On Capacitance	f = 1 MHz, Switch On, Open Output		2.0		pF
C _{OFF}	A _N to B _N , A _N to C _N	Off Capacitance	f = 1 MHz, Switch Off		1.5		pF
I _{ON}	A_N to B_N , A_N to C_N	On Leakage Current	$\label{eq:VDD} \begin{array}{l} V_{DD} = 2 \ V, \ V_{AN} = 0 \ V, \ 1.2 \ V, \ Switch \\ On \ to \ B_N/C_N, \ B_N/C_N \ pins \ are \\ unconnected \end{array}$	-1		+1	μΑ
I _{OFF}	A_N to B_N , A_N to C_N	Off Leakage Current	V_{DD} = 2 V, V_{AN} = 0 V, 1.2 V, Switch Off to $B_N/C_N,V_{BN}/V_{CN}$ = 1.2 V, 0 V	-1		+1	μA

LOGIC INPUT CHARACTERISTICS (SEL Pin)

V _{IH}	SEL	Input HIGH Voltage	(Note 7)	0.65 x V _{DD}		V _{DD}	V
V _{IL}	SEL	Input LOW Voltage	(Note 7)	0		0.35 x V _{DD}	V
V _{IK}	SEL	Clamp Diode Voltage	V _{DD} = Max, I _{SEL} = -18mA		-0.7	-1.2	V
I _{IH}	SEL	Input HIGH Current	V _{DD} = Max, V _{SEL} = V _{DD}			±5	μΑ
IIL	SEL	Input LOW Current	V _{DD} = Max, V _{SEL} = GND			±5	μA

SWITCHING CHARACTERISTICS

t _{SELON}	SEL, A _N , B _N /C _N	Line Enable Time	SEL to A_N , B_N , C_N $R_L = 50 \Omega$, $C_L = 20 \text{ pF}$	8.0	ns
tSELOFF	SEL, A _N , B _N /C _N	Line Disable Time	SEL to A _N , B _N , C _N R _L = 50 Ω , C _L = 20 pF	5.0	ns
t _{b-b}	A _N , B _N /C _N	Bit-to-bit skew	Within the same differential pair	5.0	ps
t _{ch–ch}	A _N , B _N	Channel-to channel skew	Maximum skew between all channels	50	ps

For Max. or Min. conditions, use appropriate value specified under Electrical Characteristics for the applicable device type.
Typical values are at V_{DD} = 1.8 V, T_A = 25°C ambient and maximum loading.
Guaranteed by design and/or characterization.

Symbol	Pins	Parameters	Conditions (Note 5)	Min.	Тур	Max.	Units	
					(Note 6)			

DYNAMIC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE

		O's set D't Dete			01
BR	A _N to B _N , A _N to C _N	Signal Bit Rate		8.0	Gbps
D _{IL}	$\begin{array}{c} L & A_{N} \text{ to } B_{N}, \\ A_{N} \text{ to } C_{N} \end{array}$	Differential Insertion Loss	f = 4 GHz	-2.0	dB
			f = 100 MHz	-0.7	dB
D _{CTK}	CTK A _N , B _N , C _N	B _N , C _N Differential Crosstalk	f = 4 GHz	-30	dB
			f = 100 MHz	-58	dB
D _{ISO}	IN IN/	Differential Off Isolation	f = 4 GHz	-20	dB
	A _N to C _N		f = 100 MHz	-58	dB
D _{RL}	A_N to B_N ,	A _N to B _N , Differential Return Loss	f = 4 GHz	-9.0	dB
	A _N to C _N		f = 100 MHz	-22	dB

5. For Max. or Min. conditions, use appropriate value specified under Electrical Characteristics for the applicable device type.

6. Typical values are at V_{DD} = 1.8 V, T_A = 25°C ambient and maximum loading.

7. Guaranteed by design and/or characterization.

TYPICAL OPERATING CHARACTERISTICS



Figure 4. Reference PCle 3.0 Eye Diagram without Switch at 8 Gbps, 800 mV_{pp} Differential Swing









PARAMETER MEASUREMENT INFORMATION



















Figure 14. Bit-to-Bit and Channel-to-Channel Skew



Figure 15. t_{ON} and t_{OFF}



Figure 16. Off State Leakage

Figure 17. On State Leakage

PACKAGE DIMENSIONS



BOTTOM VIEW

- DIMENSIONING AND TOLERANCING PER ASME
- CONTROLLING DIMENSION: MILLIMETERS. DIMENSION & APPLIES TO PLATED TERMINAL
- AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM TERMINAL TIP.
- COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

MOUNTING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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